Docket No.: 27-006

the specification of which

## DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office address, and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought on the invention entitled:

## SEMICONDUCTOR PACKAGE HEAT SPREADERS AND FABRICATION METHODS THEREFOR

is attached hereto
was filed on as Application Serial No and was amended on (if applicable).
I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.
I do not know and do not believe the same was ever known or used in the United States of America before this invention thereof or more than one year prior to this application, and that the same was not in public use or on sale in the United States of America more than one year prior to this application. I acknowledge the duty to disclose information which is known to me to be material to patentability in accordance with title 37, Code of Federal Regulations, section 1.56.
I hereby claim foreign priority benefits under Title 35, United States Code, Section 119(a)-(d) or Section 365(b) of any foreign application(s) for patent or inventor's certificate, or Section 365(a) of any PCT international application which designated at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:
Prior Foreign Application(s):
Number Country Day/Month/Year filed Yes No
I hereby claim the benefit under 35 USC 119(e) of any United States provisional application(s) listed below:
Prior Provisional Application(s):
Application Number Filing Date
I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s), or Section 365(c) of any PCT international application designating the

acknowledge the duty to disclose material information as defined in Title 37, Code of Federal

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Regulations, Section 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

## Prior U.S. Application(s):

Serial No.

Filing Date

Status: Patented, Pending, Abandoned

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby revoke any previous Powers of Attorney and appoint the following attorney(s) and/or agent(s), each said individual being a member or associate of The Law Offices of Mikio Ishimaru or being employed by ST Assembly Test Services Ltd.:

Mikio Ishimaru

Reg. No. 27,449

William D. Zahrt, II

Reg. No. 26,070

Date: 18 Nov., 2003

for so long as they remain with such law offices or company with full power of substitution and revocation, to prosecute this application and to transact in connection therewith all business in the Patent and Trademark Office and before competent International Authorities; said appointment to be to the exclusion of myself and my other attorney(s); and all future correspondence should be addressed to:

Mikio Ishimaru The Law Offices of Mikio Ishimaru 1110 Sunnyvale – Saratoga Rd., Suite A1 Sunnyvale, California 94087

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Virgil Cotoco Ararao

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Date: Nov. 18,2003 Inventor's signature: IL Kwon Shim Full name of joint inventor: Citizenship: **Korea** Residence Address, including Blk 10 Woodgrove Drive #04-33 Woodgrove Condo country: Singapore 738211 Singapore Post Office Address: ST Assembly Test Services Ltd. 5 Yishun Street 23 Singapore 768442 Singapore Date: Nov. 18, 2003 Inventor's signature: Full name of joint inventor: Seng Guan Chow Citizenship: Malaysia Residence Address, including Blk 131 Yishun Street 11 country: #07-243 Singapore 760131 Singapore ST Assembly Test Services Ltd. Post Office Address: 5 Yishun Street 23 Singapore 768442 Singapore Date: Nov. 18, 2003 Inventor's signature: Sheila Marie L. Alvarez Full name of joint inventor: **Philippines** Citizenship: Residence Address, including 526 Woodlands Drive 14 #07-463 country: Singapore 730526 Singapore P.O. Address: ST Assembly Test Services Ltd.

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